



Material Content Data Sheet



Sales Product Name	IFX1021SJ			Issued		18. March 2016		
MA#	MA001473120							
Package	PG-DSO-8-16			Weight*		83.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.228	2.67	2.67	26735	26735
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		430	
	non noble metal	iron	7439-89-6	0.717	0.86		8608	
	non noble metal	copper	7440-50-8	29.121	34.95	35.86	349510	358656
wire	noble metal	gold	7440-57-5	0.213	0.26	0.26	2556	2556
encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1159	
	plastics	epoxy resin	-	4.443	5.33		53324	
	inorganic material	silicondioxide	60676-86-0	43.753	52.52	57.97	525124	579607
leadfinish	non noble metal	tin	7440-31-5	0.824	0.99	0.99	9890	9890
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7804	7804
glue	plastics	acrylic resin	-	0.270	0.32		3245	
	noble metal	silver	7440-22-4	0.959	1.15	1.47	11507	14752
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

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2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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